

AMENDMENTS TO THE CLAIMS:

Amend the claims as follows:

1. (Currently Amended) A solar cell having an electrode coated with lead-free solder, wherein phosphorus is included in said lead-free solder, and said solder is a Sn-Ag based solder not containing Bi, said solder containing 3.5 mass% to 4.5 mass% Ag and phosphorous in an amount of 0.005 to 0.0001 mass %

said electrode being a silver electrode formed by firing silver paste, said silver paste comprising a powdery glass, said powdery glass has an average particle size of 5 μ m to 20 μ m.

Claim 2. (Canceled)

3. (Currently Amended) A solar cell having an electrode coated with lead-free solder, wherein phosphorus is included in said lead-free solder, wherein said lead-free solder is Sn-Bi-Ag based solder with a Bi content of greater than 5 mass % to ~~[[89]]~~88 mass % ~~and the solder has a melting point of 193-195°C~~ and containing an amount of phosphorous in an amount of 0.005 to 0.0001 mass %.

said electrode being a silver electrode formed by firing silver paste, said silver paste comprising a powdery glass, said powdery glass has an average particle size of 5 μ m to 20 μ m.

4. (Currently Amended) The solar cell according to claim 3 wherein the powdery glass has an average particle size of 5 μ m to 11 μ m ~~any one of claims 1, 3, 15 and 16,~~
~~wherein said electrode is a silver electrode formed by firing silver paste.~~

5. (Currently Amended) The solar cell according to claim 4, wherein the powdery glass has an average particle size of an average grain size of powdery glass included in
~~said silver paste is 11 μ m at most.~~

6. (Currently Amended) The solar cell according to claim 4 or claim 5, wherein
an amount of powdery glass included in said silver paste is 2.8 to ~~[[10.0]]~~ 4 mass %.

7. (Currently Amended) The solar cell according to claim 4 or claim 5, wherein
said silver paste has an average thickness of ~~at least 15 μ m~~ to 20 μ m.

8. (Withdrawn – Currently Amended) A fabrication method of a solar cell
comprising the steps of printing silver paste at a partial region at a light receiving side of
an anti-reflection film and at a partial region at a back side of a p type silicon substrate,
firing said silver paste to form a silver electrode, and coating said silver electrode with
lead-free solder including phosphorus as in either claim 1 or claim 3 ~~of any one of claims~~
~~1, 3, 15 and 16~~, wherein powdery glass sifted through a sieve having an opening
diameter of 73 μ m at most is used as said powdery glass included in said silver paste.

9. (Withdrawn – Currently Amended) A fabrication method of a solar cell comprising the steps of printing silver paste at a partial region at a light receiving side of an anti-reflection film and at a partial region at a back side of a p type silicon substrate, firing said silver paste to form a silver electrode, and coating said silver electrode with lead-free solder including phosphorus as in either claim 1 or claim 3~~according to any one of claims 1, 3, 15 and 16~~, wherein the step of printing silver paste includes applying silver paste at least two times.

10. (Withdrawn – Currently Amended) A fabrication method of a solar cell comprising the steps of printing silver paste at a partial region at a light receiving side of an anti-reflection film and at a partial region at a back side of a p type silicon substrate, firing said silver paste to form a silver paste electrode, and coating said silver paste electrode with lead-free solder including phosphorus as in either claim 1 or claim 3~~according to any one of claims 1, 3, 15 and 16~~, wherein the step of printing silver paste includes applying silver paste using a mask having a thickness of three times a wire diameter.

Claims 11-14. (Canceled)

15. (Currently Amended) The [[A]] solar cell as in one of claims 3-5 wherein the Bi content of said solder is in the range of 35 mass % to 60 mass %~~having an electrode coated with lead-free solder, wherein phosphorus is included in said lead-free solder,~~

~~wherein said lead-free solder is Sn-Bi-Ag based solder with a Bi content of greater than 5 mass % to 89 mass % and a Ag content of 0.1 to 1.3 mass %.~~

16. (Currently Amended) The [[A]] solar cell as in one of claims 3-5 wherein the Bi content of said solder is in the range of 27 mass % to 79 mass % and said solder contains 0.1 mass % Ag~~having an electrode coated with lead-free solder, wherein phosphorus is included in said lead-free solder, wherein said lead-free solder is Sn-Bi-Ag based solder with a Bi content of 27 to 79 mass %.~~

17. (Currently Amended) ~~The solar cell of any one of claims 3, 15 and 16 wherein the Bi content of said solder is 35 to 60 mass %~~

The solar cell as in claim 6 wherein the Bi content of said solder is in the range of 27 mass % to 79 mass % and said solder contains 0.1 mass % Ag.

18. (Currently Amended) ~~The solar cell of any one of claims 3 and 15 wherein the Bi content of said solder is 27 to 79 mass %.~~

The solar cell as in claim 7 wherein the Bi content of said solder is in the range of 27 mass % to 79 mass % and said solder contains 0.1 mass % Ag

19. (new) The solar cell according to claim 1 wherein the powdery glass has an average particle size of 5 μm to 11 μm .

20. (new) The solar cell according to claim 19, wherein the powdery glass has an average particle size of 11 μm .

21. (new) The solar cell according to claim 19 or claim 20, wherein an amount of powdery glass included in said silver paste is 2.8 to 4 mass %.

22. (new) The solar cell according to claim 19 or claim 20, wherein said silver paste has an average thickness of 15 μm to 20 μm .

23. (new) The solar cell as in claim 6 wherein the Bi content of said solder is in the range of 35 mass % to 60 mass %.

24. (new) The solar cell as in claim 7 wherein the Bi content of said solder is in the range of 35 mass % to 60 mass %.